



DGD21844

HALF- BRIDGE GATE DRIVER IN SO-14

Description

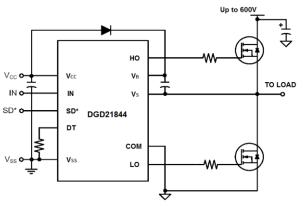
The DGD21844 is a high voltage / high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD21844's high-side to switch to 600V in a bootstrap operation.

The DGD21844 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. Programmable deadtime, by an external resistor, provides more system level flexibility.

The DGD21844 is offered in SO-14 (Type TH) package, the operating temperature extends from -40°C to +125°C.

Applications

- **DC-DC** Converters
- **DC-AC Inverters**
- **AC-DC Power Supplies**
- Motor Controls
- **Class D Power Amplifiers**



Typical Configuration

Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD21844S14-13	DGD21844	13	16	2,500

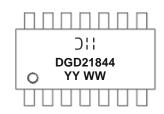
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

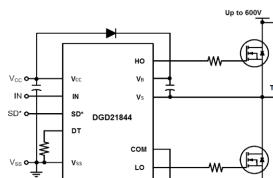
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



DH = Manufacturer's marking DGD21844 = Product Type Marking Code YY = Year (ex: 16 = 2016) WW = Week (01 to 53)



Features

- Floating High-side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in Half Bridge Configuration
- 1.4A Source / 1.8A Sink Output Current Capability
- **Outputs Tolerant to Negative Transients**
- Programmable Dead Time to Protect MOSFETs •
- Wide Low-side Gate Driver and Logic Supply: 10V to 20V
- Wide Logic Supply Voltage Offset Voltage:-5V to 5V
- Logic Input (IN and SD*) 3.3V Capability •
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout for High and Low Side Drivers
- Extended Temperature Range: -40°C to +125°C •
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

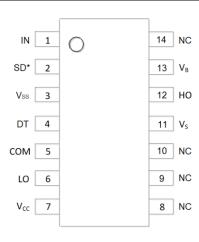
- Case: SO-14 (Type TH)
- Case material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.142 grams (Approximate)



SO-14 (Type TH) Top View



Pin Diagrams

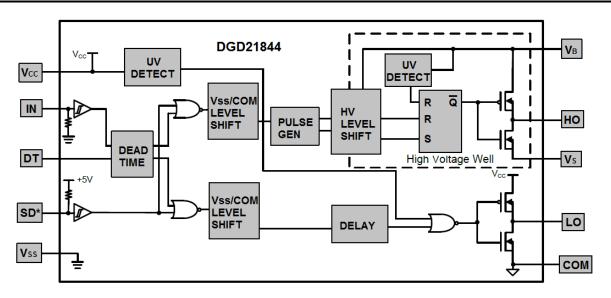


Top View SO-14 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	IN	Logic input for high-side and low-side gate driver outputs (HO and LO), in phase with HO (Referenced to V _{SS})
2	SD*	Logic input for shutdown (Referenced to V _{SS}), enabled low
3	V _{SS}	Logic ground
4	DT	Programmable deadtime lead (Referenced to V _{SS})
5	COM	Low-side return
6	LO	Low-side gate drive output
7	Vcc	Low-side and logic fixed supply
8,9,10,14	NC	No Connect (No Internal Connection)
11	Vs	High-side floating supply return
12	HO	High-side gate drive output
13	VB	High-side floating supply

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	VB	-0.3 to +624	V
High-side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Programmable Dead Time Pin Voltage	V _{DT}	V _{SS} -0.3 to V _{CC} +0.3	V
Logic and Low-side Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Supply Offset Voltage	V _{SS}	V _{CC} -24 to V _{CC} +0.3	V
Logic Input Voltage (IN and SD*)	V _{IN}	V _{SS} -0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear derating factor (Note 5)	PD	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	120	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (soldering, 10s)	TL	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-side Floating Supply Absolute Voltage	VB	V _S + 10	V _S + 20	V
High-side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-side Floating Output Voltage	V _{HO}	Vs	VB	V
Logic and Low-side Fixed Supply Voltage	Vcc	10	20	V
Low-side Output Voltage	V _{LO}	0	V _{CC}	V
Logic Input Voltage (IN and SD*)	V _{IN}	V _{SS}	5	V
Programmable Dead Time Pin Voltage	V _{DT}	Vss	Vcc	V
Logic Ground	V _{SS}	-5	5	V
Ambient Temperature	T _A	-40	+125	°C

Note: 6. Logic operation for $V_S = -5V$ to +600V. Logic state held for V_S of -5V to - V_{BS} .



DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, V_{SS} = COM, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage for HO & Logic "0" for LO	VIH	2.5	-	-	V	$V_{CC} = 10V$ to 20V
Logic "0" Input Voltage for HO & Logic "1" for LO	VIL	-	-	0.8	V	$V_{CC} = 10V$ to 20V
SD* Input Positive Going Threshold	V _{SDTH+}	2.5	-	-	V	$V_{CC} = 10V$ to 20V
SD* Input Negative Going Threshold	V _{SDTH-}	_	-	0.8	V	V_{CC} = 10V to 20V
High Level Output Voltage, V _{BIAS} - V _O	V _{OH}	—	-	1.4	V	$I_{O} = 0 m A$
Low Level Output Voltage, Vo	Vol	_	-	0.2	V	$I_0 = 20 \text{mA}$
Offset Supply Leakage Current	I _{LK}	—	-	50	μA	$V_{\rm B} = V_{\rm S} = 600 V$
Quiescent V _{BS} Supply Current	I _{BSQ}	20	60	150	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent V _{CC} Supply Current	ICCQ	0.4	1.0	1.8	mA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I _{IN+}	_	25	60	μA	$IN = 5V, SD^* = 0V$
Logic "0" Input Bias Current	I _{IN-}	_	-	1.0	μA	IN = 0V, SD* = 5V
V _{BS} Supply Under-voltage Positive Going Threshold	V _{BSUV+}	8.0	8.9	9.8	V	-
V _{BS} Supply Under-voltage Negative Going Threshold	V _{BSUV-}	7.4	8.2	9.0	V	-
V _{CC} Supply Under-voltage Positive Going Threshold	V _{CCUV+}	8.0	8.9	9.8	V	-
V _{CC} Supply Under-Voltage Negative Going Threshold	V _{CCUV} -	7.4	8.2	9.0	V	-
Output High Short Circuit Pulsed Current	I _{O+}	1.4	1.9	-	А	V _O = 0V, PW ≤ 10µs
Output Low Short Circuit Pulsed Current	I _{O-}	1.7	2.3	-	А	V _O = 15V, PW ≤ 10µs

Note:

7. The V_{IN} and I_{IN} parameters are referenced to V_{SS} and are applicable to the two logic input pins: IN and SD*. The V₀ and I₀ parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, V_{SS} = COM, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay	t _{ON}	-	680	900	ns	$V_{\rm S} = 0V$
Turn-off Propagation Delay	tOFF	-	270	400	ns	$V_{S} = 0V \text{ or } 600V$
Shut-down Propagation Delay	t _{SD}	-	180	270	ns	-
Delay Matching, HO & LO Turn-on	tDMON	-	-	90	ns	-
Delay Matching, HO & LO Turn-off	t DMOFF	-	-	40	ns	-
Turn-on Rise Time	t _R	-	40	60	ns	$V_{\rm S} = 0V$
Turn-off Fall Time	tF	-	20	35	ns	$V_{S} = 0V$
Deadtime: t _{DT LO-HO &} t _{DT HO-LO}		280	400	520	ns	$R_{DT} = 0\Omega$
	t _{DT}	4	5	6	μs	R _{DT} = 200KΩ
		_	0	50	ns	$R_{DT} = 0\Omega$
Deatime Matching = t _{DT LO-HO} - t _{DT HO-LO}	t _{MDT}	_	0	600	ns	R _{DT} = 200KΩ



Timing Waveforms

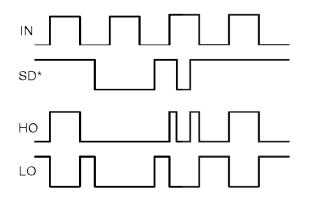


Figure 1. Input / Output Timing Diagram

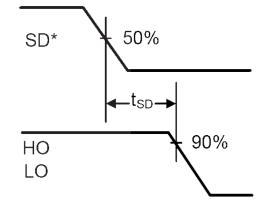
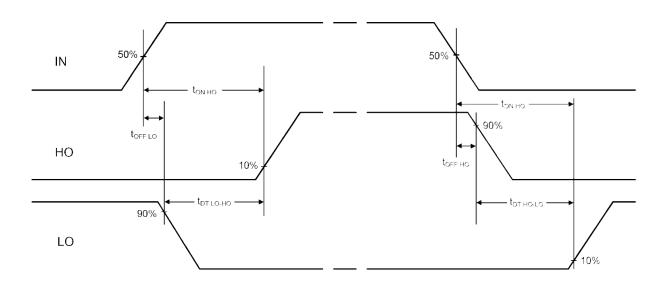


Figure 2. Shutdown Waveform Definitions

 $\begin{array}{l} \textbf{Delay matching} \\ t_{\text{DM OFF}} = t_{\text{OFF LO}} - t_{\text{OFFT HO}} \end{array}$



 $\begin{array}{l} \text{Deadtime } t_{\text{DT LO-HO}} = t_{\text{ON HO}} \text{-} t_{\text{OFF LO}} \\ t_{\text{DT HO-LO}} = t_{\text{ON LO}} \text{-} t_{\text{OFF HO}} \end{array}$

Deadtime matching $t_{MDT} = t_{DT LO-HO} - t_{DT HO-LO}$

Figure 3. Switching Time Waveform Definitions



Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.)

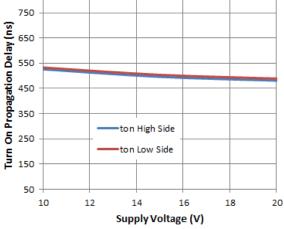


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

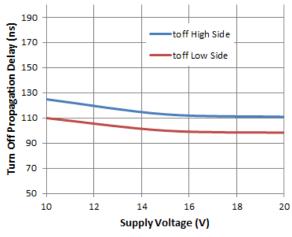
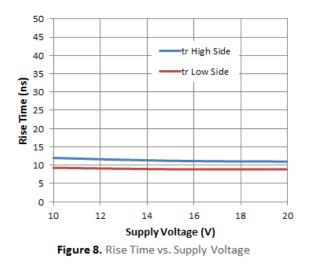


Figure 6. Turn-off Propagation Delay vs. Supply Voltage



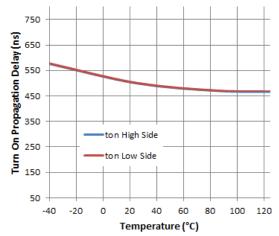


Figure 5. Turn-on Propagation Delay vs. Temperature

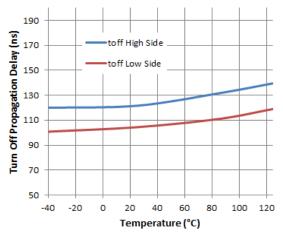
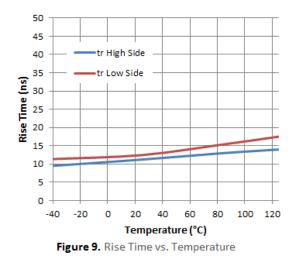
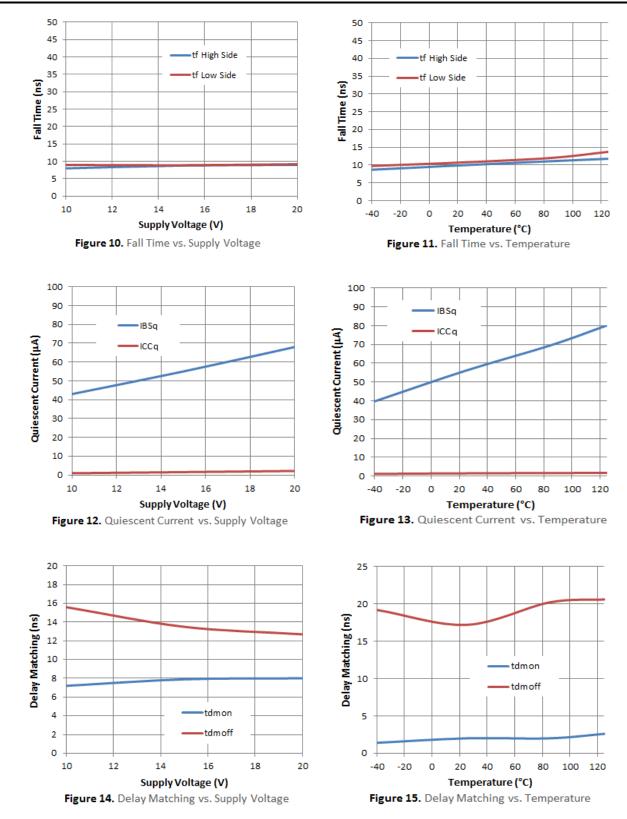


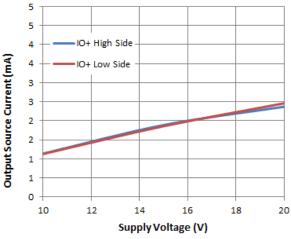
Figure 7. Turn-off Propagation Delay vs. Temperature











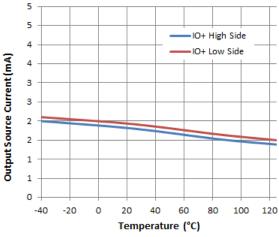
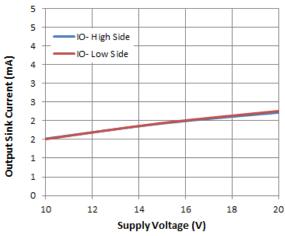


Figure 16. Output Source Current vs. Supply Voltage





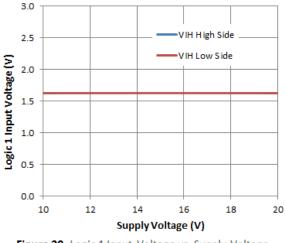
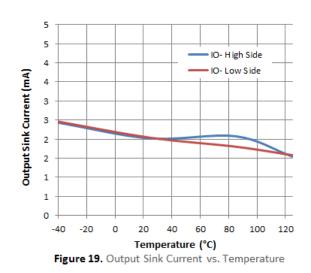


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

Figure 17. Output Source Current vs. Temperature



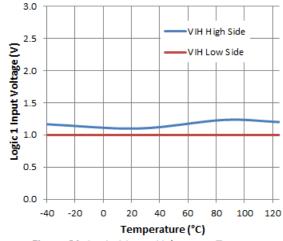
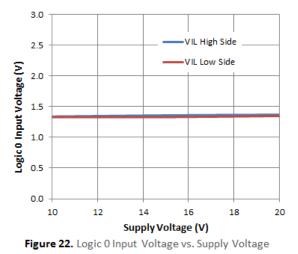
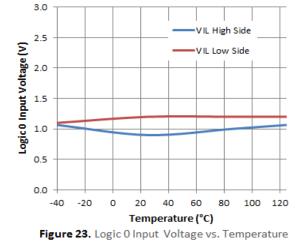
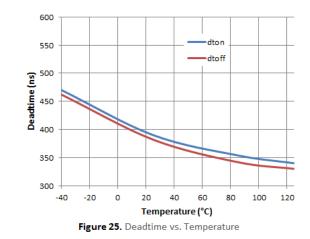


Figure 21. Logic 1 Input Voltage vs. Temperature









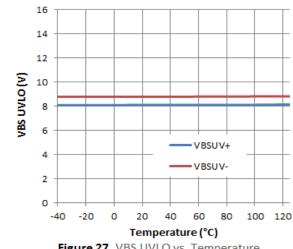
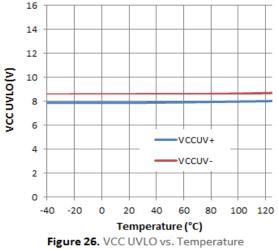




Figure 27. VBS UVLO vs. Temperature

600 dton 550 dtoff 500 Deadtime (ns) 450 400 350 300 12 20 10 14 16 18 Supply Voltage (V)

Figure 24. Deadtime vs. Supply Voltage





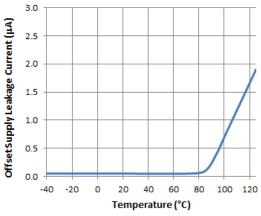


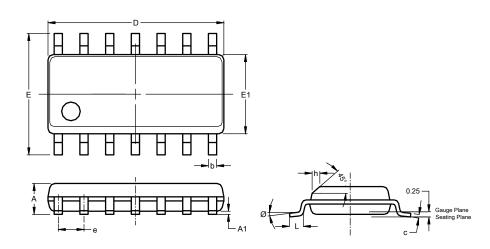
Figure 28. Offset Supply Leakage Current vs. Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

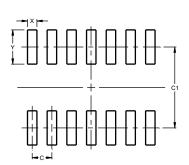
SO-14 (Type TH)



S	SO-14 (Type TH)					
Dim	Min	Max	Тур			
Α	1.55	1.73				
A1	0.10	0.25				
b	0.35	0.51				
С	0.190	0.248				
D	8.56	8.74	8.61			
Е	5.84	6.20	6.00			
E1	3.81	3.99	3.94			
е			1.27			
h			0.33			
L	0.41	0.89				
Ø	0°	8°				
All C	All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	1.27
C1	5.20
Х	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

SO-14 (Type TH)



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